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Attorney Docket: 8054-80 (LW9122US/CW)

Form PTO-1595
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HEET

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102952870

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Seong-Yong Hwang, Week-Sik Oh, Ju-Young Yoon,
Sung-Lak Choi, Chun-Ho Song

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: January 26, 2005

2. Name and address of receiving party(ies):

Name: SAMSUNG ELECTRONICS CO., LTD.

Internal Address: 416, Maetan-dong, Yeongtong-gu,
Suwon-si, Gyeonggi-do, Korea 442-742

Additional name(s) & address(es) attached:

☐ Yes ☒ No

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4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:
January 26, 2005

A. Patent Application No.(s) 10/970,360

Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

**5. Name and address of party to whom
correspondence concerning document
should be mailed:**

Name: Frank Chau, Esq.

Street Address: F. CHAU & ASSOCIATES, LLC
130 Woodbury Road

City: Woodbury State: NY Zip: 11797

**6. Total number of applications and
patents involved: 1**

7. Total fee (37 C.F.R. §3.41): \$40.00

- ☒ Credit Card Payment Form PTO-2038
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account

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Frank Chau

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Date 2/28/05

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PATENT
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ASSIGNMENTDOCKET NO.: 8054-80 (LW9122US/CW)

AS A BELOW NAMED INVENTOR, I, and each of us, individually hereby declare that: IN CONSIDERATION of the sum of TEN (\$10.00) dollars or the equivalent thereof, and other good and valuable consideration, the receipt of which from the hereinafter named Assignee is hereby acknowledged, I do hereby sell, assign and forever grant and convey unto:

ASSIGNEE: Samsung Electronics Co., Ltd.

ADDRESS: 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, KOREA

Who is my Assignee, and to the successes and assigns of my Assignee, all my right, title and interest, in and for the United States of America and all other countries, including all rights of priority, in and to the invention entitled:

TITLE: **ANISOTROPIC CONDUCTIVE FILM AND BUMP, AND PACKAGING
STRUCTURE OF SEMICONDUCTOR HAVING THE SAME**

invented by me (*if only one inventor is named below*) or us (*if more than one inventor is named below*) and described in an application for a United States patent the specification of which is either attached hereto or otherwise accompanies this Assignment or indicates an attorney docket no. _____, or is more particularly identified as:

- ☐ executed on even date herewith, or
☐ Serial No. 10/970,360 filed in the U.S. Patent & Trademark Office on October 21, 2004,
or
☐ executed on _____,

and in and to all United States patents which may be granted thereon and therefore, and in and to all certificates of corrections, divisions, continuations, continuations-in-part, reissued and re-examined patents, and to any extensions thereof, said interest being the entire ownership of the patent when granted, to be held and enjoyed by said **SAMSUNG ELECTRONICS CO., LTD.**, my Assignee, its successors, assigns or other legal representatives, to the full end of the term, terms, or any extension or renewal thereof, for which said patent or patents may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment, sale and conveyance had not been made;

AND I hereby covenant and agree to sign and execute any further documents or instruments which may from time-to-time be either necessary, lawful, proper or requested by the Assignee, in the prosecution of the above-named application or in the preparation and prosecution of any certificate of correction, division, continuation, continuation-in-part, reissue, re-examination, in any amendment, extension, or interference proceeding, whether administrative or judicial, or otherwise, to secure the title hereto in said Assignee;

AND I do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Patent or Patents to the Assignee, and I hereby appoint as my, or our attorney, and authorize and request Frank Chau, Reg. No. 34,136, to insert on this Assignment any further identification or to complete such identification which may be either necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

I HEREBY DECLARE that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under ' 1001 of Title 18 U.S. Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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Inventor's signature: SEONG-YONG HWANG Date: 01/26/05

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